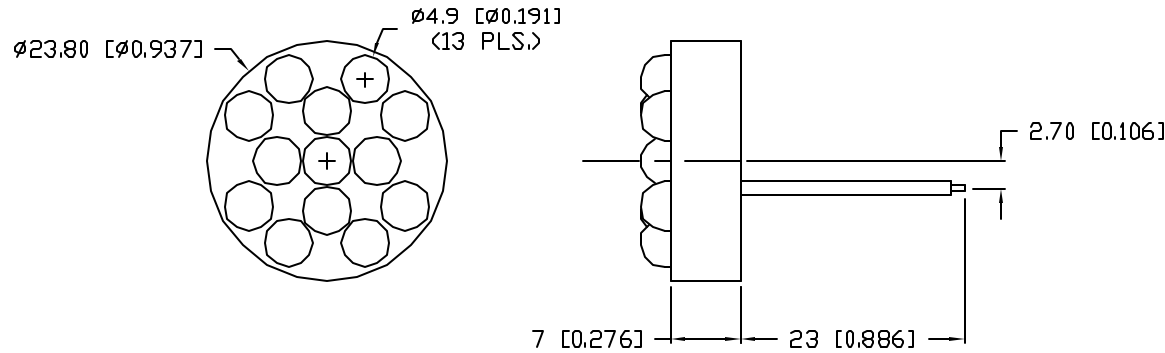


UNCONTROLLED DOCUMENT

PART NUMBER
SSP-LXC0947U13A

REV.
C

REV.	E.C.N. NUMBER AND REVISION COMMENTS	DATE
A	E.C.N. #10556.	10.13.99
B	E.C.N. #10582.	1.14.00
C	E.C.N. #10650.	8.16.00



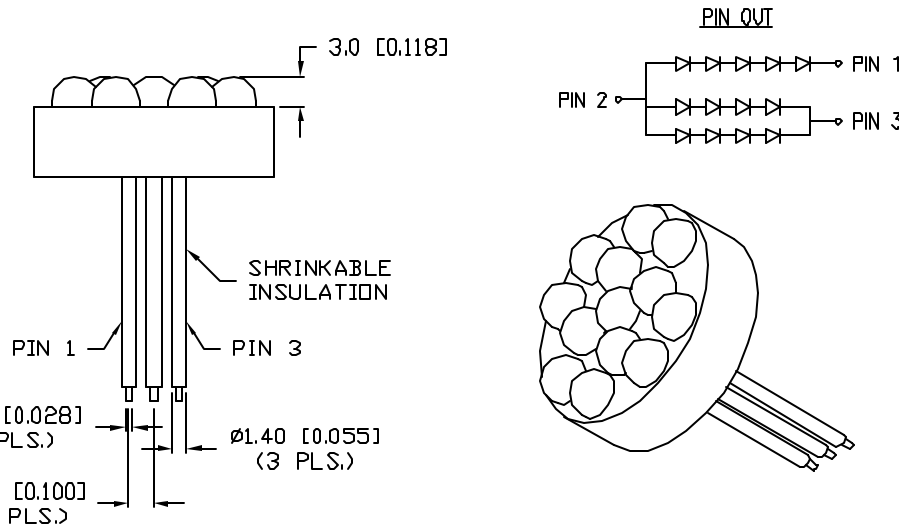
ELECTRO-OPTICAL CHARACTERISTICS $T_A=25^\circ\text{C}$ $I_f=20/40\text{mA}$

PARAMETER	MIN	TYP	MAX	UNITS	TEST COND
PEAK WAVELENGTH		470		nm	
FORWARD VOLTAGE*		17.5/14	20/16	V_f	
REVERSE VOLTAGE	5.0			V_r	$I_r=100\mu\text{A}$
AXIAL INTENSITY**		2000		mcd	$I_f=20/40\text{mA}$
VIEWING ANGLE		30		2x theta	

EMITTED COLOR: ULTRA BLUE
EPOXY LENS FINISH: WATER CLEAR

* VOLTAGE FOR: PIN 1/PIN 3

** INTENSITY PER DIE. TEST CONDITION: CURRENT FOR PIN 1/PIN 3



LIMITS OF SAFE OPERATION AT 25°C PER DIE

PARAMETER	MAX	UNITS
PEAK FORWARD CURRENT*	100	mA
STEADY CURRENT	30	mA
POWER DISSIPATION	98	mW
DERATE FROM 25°C	-1.0	mW/ $^\circ\text{C}$
OPERATING, STORAGE TEMP.	-30 TO +70	$^\circ\text{C}$
SOLDERING TEMP.	+260	$^\circ\text{C}$
2.0mm FROM BODY		3 SEC. MAX

* $t < 10\mu\text{s}$

CAUTION: STATIC SENSITIVE DEVICE
FOLLOW PROPER E.S.D. HANDLING PROCEDURES
WHEN WORKING WITH THIS PART.
ESD CLASSIFICATION: CLASS II BASED ON MIL-STD 883E.

*UNLESS OTHERWISE SPECIFIED TOLERANCES PER DECIMAL PRECISION ARE: X=±1 (±0.039), X.X=±0.5 (±0.020), X.XX=±0.25 (±0.010), X.XXX=±0.127 (±0.005). LEAD SIZE=±0.05 (±0.002), LEAD LENGTH=±0.75 (±0.030), MIN= ^{+DECIMAL PRECISION} -0.00 MAX= ^{+0.00} -DECIMAL PRECISION

UNCONTROLLED DOCUMENT

REV. C PART NUMBER SSP-LXC0947U13A

CONFIDENTIAL INFORMATION
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0.94" CIRCULAR, 13 LED POLYLED,
470nm InGaN/SiC BLUE LEDES, WATER CLEAR LENS.

RELIABILITY NOTE
DUR MANY YEARS OF EXPERIENCE DATA ACCUMULATION INDICATE THAT SOLDER HEAT IS A MAJOR CAUSE OF EARLY AND FUTURE FAILURE. PLEASE PAY ATTENTION TO YOUR SOLDERING PROCESS.

DRAWN: BC CHECKED: APPROVED: DATE: 9.21.99
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